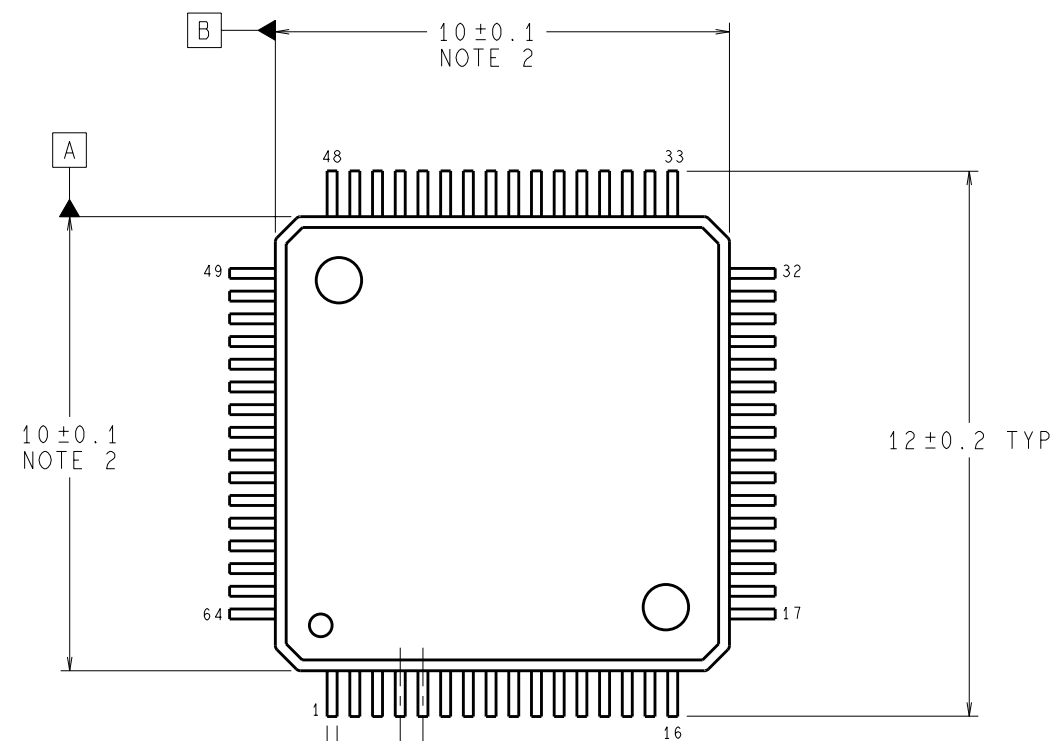
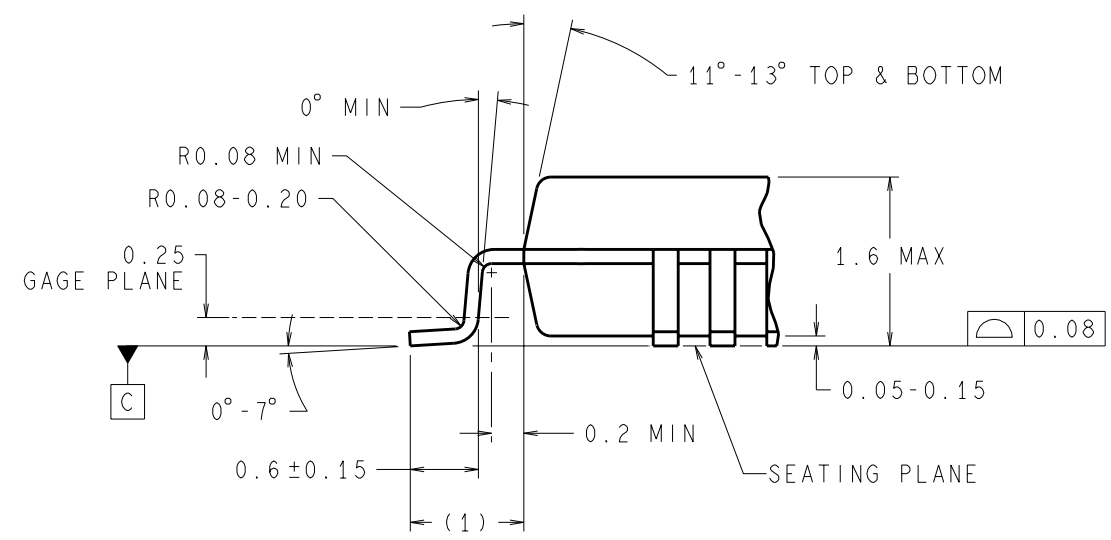
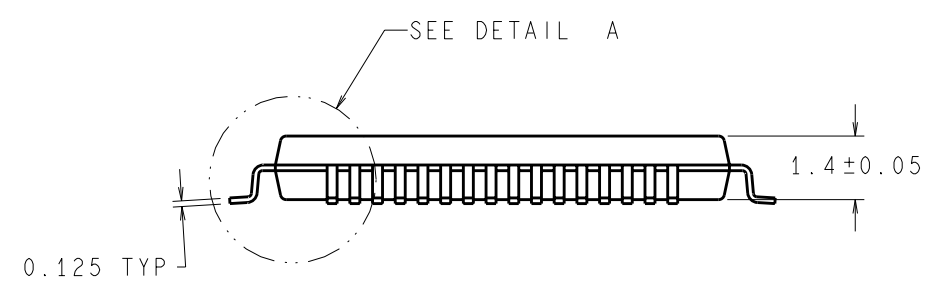


| REVISIONS | | | | |
|-----------|--|--------|------------|-----------|
| LTR | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| C | TITLE: LOFP WAS PQFP; DELETE NOTE 3; UPDATE NEW NOTE 3; ADD GEOMETRIC TOLERANCE; REDRAW. | 12317 | 12/01/1999 | ACS/MS/RW |



0.5 TYP
 0.22 ± 0.05 TYP
 ⊕ 0.08 M C A ⊖ B ⊖



DETAIL A
 TYP, SCALE: 25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15) THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BCD, DATED FEB 1999.

| | | | | | |
|-------------------------------|------------|---|-----------|----------------------------------|----------|
| APPROVALS | DATE | National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090 | | | |
| DRAWN MARTA SUCHY | 12/01/1999 | | | | |
| DFTG. CHK. THANH LEQUANG | 12/08/1999 | | | | |
| ENGR. CHK. RANDALL WALBERG | 12/08/1999 | LOFP, JEDEC METRIC, 10 X 10 X 1.4mm, 64 LEAD | | | |
| PROJECTION INCH [MM] | | SCALE N/A | SIZE C | DRAWING NUMBER (SC)MKT-VEH64A | REV C |
| FORMERLY: | | SHEET 1 of 1 | | | |